



2304051441 Alternate PCB Supplier for xGM210P Modules

PCN Issue Date: Apr 05, 2023

Effective Date: Jul 11, 2023

PCN Type: Assembly

Description of Change

Silicon Labs is pleased to announce the successful qualification of a new Printed Circuit Board (PCB) supplier for xGM210P modules in Ryder. Upon PCN effective date, Silicon Labs will begin shipping the modules listed below with new PCB supplier.

Reason for Change

New PCB supplier qualification to mitigate supply constraint.

Impact on Form, Fit, Function, Quality, Reliability

There is no change in form, fit, function, quality & reliability performance.

Product Identification

This notification includes both standard and customer-specific part numbers. An asterisk * represents a number or letter (one or more) in a customer-specific part number.

Existing Part #
BGM210PA22JIA2
BGM210PA22JIA2R
BGM210PA32JIA2
BGM210PA32JIA2R
BGM210PB22JIA2
BGM210PB22JIA2R
BGM210PB32JIA2
BGM210PB32JIA2R
MGM210PA22JIA2
MGM210PA22JIA2R
MGM210PA32JIA2
MGM210PA32JIA2R
MGM210PB22JIA2
MGM210PB22JIA2R
MGM210PB32JIA2
MGM210PB32JIA2R
MM21PA3IP*A2
MM21PA3IP*A2R
BGM210PB*1A2
BGM210PB*1A2R

Last Date of Unchanged Product: Jul 11, 2023

Qualification Samples

Samples available upon request.

Customer Response

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change, Ref. JEDEC-J-STD-046.

To request further data or inquire about this notification, please contact your Silicon Labs sales representative. A list of Silicon Labs sales representatives is available at <http://www.silabs.com>.

Customers may approve early PCN acceptance by emailing approval, along with PCN # to PCNEarlyAcceptance@silabs.com

User Registration

Register today to create your account on Silabs.com. Your personalized profile allows you to receive technical document updates, new product announcements, “how-to” and design documents, product change notices (PCN) and other valuable content available only to registered users. <http://www.silabs.com/profile>

Qualification Data

Qualification report is attached.

BGM210P, MGM210P Qualification Report



BGM210P, MGM210P, Ryder China, USI Taiwan							
Test Name	Test Condition	Qualification	Lot ID or Start	Fail/Pass or End	Notes	Summary	Status
Test Group A – Accelerated Environment Stress Tests							
Preconditioning	JESD22-A113 MSL3: 260°C 30°C / 60%RH / 192 Hr	1 lot, N=>10	Q046125	0/12	4	4 lots 0/78	Pass
			Q044122	0/24	3		
			Q046242	0/30	3		
			Q050079	0/12	5		
Temp Cycle	JESD22-A104 Cond G: -40°C to 125°C 850 cycles	1 lot, N=>10	Q046207	0/10	1,4	3 lots 0/34	Pass
			Q044119	0/12	1,3		
			Q050132	0/12	1,5		
Temp Cycle	JESD22-A104 Cond N: -40°C to 85°C 1500 cycles	1 lot, N=>10	Q044120	0/12	1,3	1 lot 0/12	Pass
Temp Humidity Bias	JESD22-A101 85°C, 85% RH 500 hours	1 lot, N=>25	Q046243	0/30	1, 2, 3	1 lot 0/30	Pass
Test Group C – Package Assembly Integrity Tests							
Mechanical Shock	JESD22-B110, Cond. B (1500g)	1 lot, N=>10	Q046221	0/10	4	3 lots 0/30	Pass
			Q044125	0/10	3		
			Q050123	0/10	5		
Mechanical Vibration	JESD22-B103, Cond. 1 (20-2000Hz)	1 lot, N=>10	Q046222	0/10	4	3 lots 0/30	Pass
			Q044126	0/10	3		
			Q050124	0/10	5		
Cleanliness Assessment	IPC-TM-650 2.3.28B	1 lot, N=>10	Q046223	0/10	4	3 lots 0/30	Pass
			Q044127	0/10	3		
			Q050131	0/10	5		

Notes:

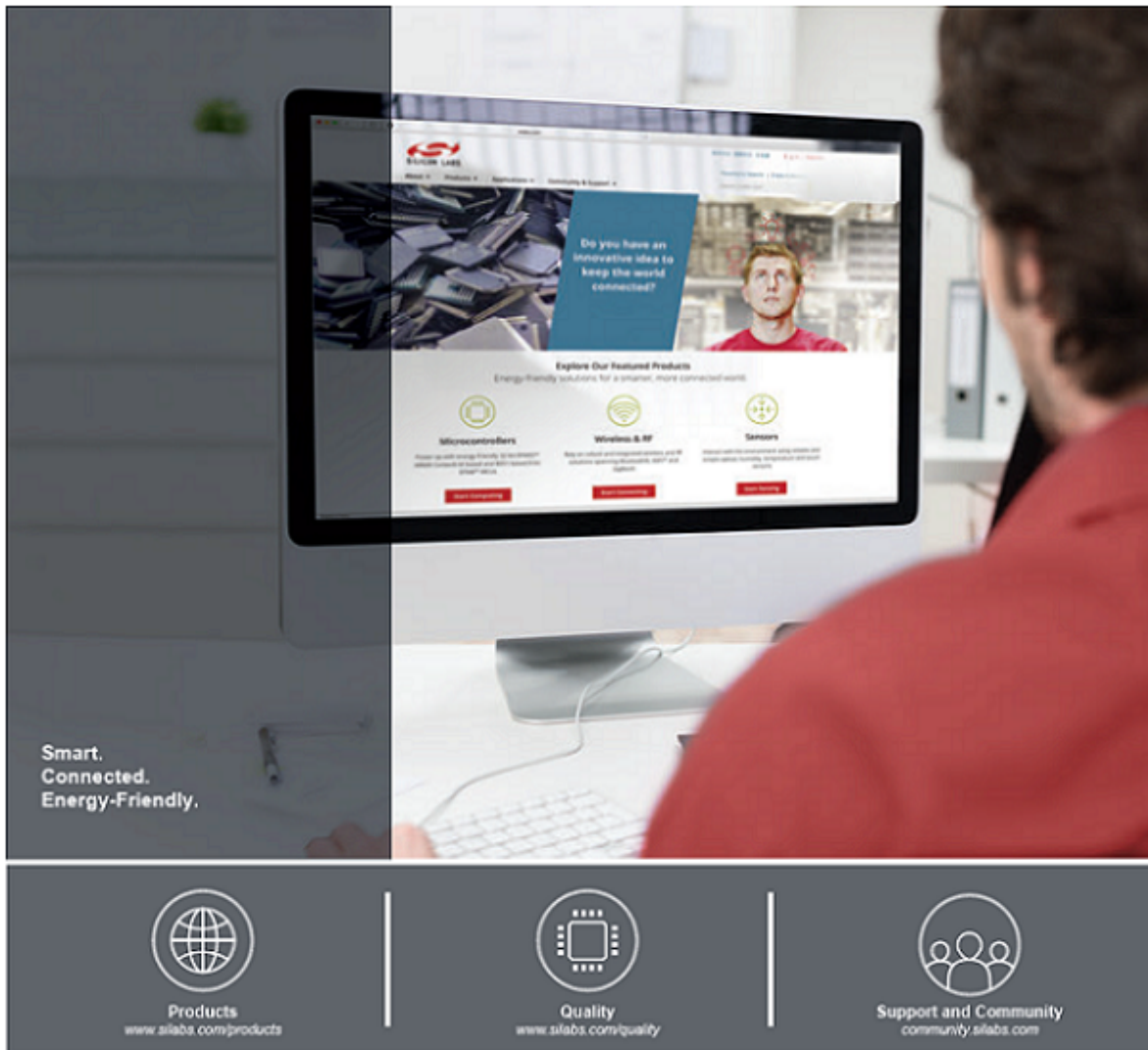
1. Parts are Pre-conditioned at MSL3/260°C
2. Additional stress test for BSH (Abbrev H3TRB)
3. Assembly in Ryder China
4. Assembly in USI Taiwan
5. Assembly in Ryder, China (KinWong PCB)

This report applies to the following part numbers:
BGM210P
MGM210P

Approved by: Wilson Choy

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Prepared on: 16-Mar-23



Disclaimer

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Silicon Laboratories Inc.
400 West Cesar Chavez
Austin, TX 78701

<http://www.silabs.com>